



PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10001302	FILING DATE 11/01/2001	CLASS 257	SUBCLASS 503	GAU 2815	EXAMINER <i>George Lee</i>
**APPLICANTS: Zuniga-Ortiz Edgar; Koduri Sreenivasan; <i>S. Christa</i>					
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PG-PUB DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO TI-33535	
TITLE : Bumpless wafer scale device and board assembly					
U.S. DEPT. OF COMM., PAT. & TM. PTO-436L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims <input type="checkbox"/> Print Claim for O.G. <input type="checkbox"/>	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig. <input type="checkbox"/>	
<input type="checkbox"/> TERMINAL		Application Examiner	
DISCLAIMER		PREPARED FOR ISSUE	
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